



Advances in Thermoelectric Materials and Technologies

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Message from the Guest Editors

This Special Issue seeks original research and review articles in the latest TE and TEG research, including high-performance TE materials, efficient and reliable device design and integration, and practical applications of TE in various fields. Topics covered include but are not limited to:

- Advance thermoelectric materials—synthesis and characterization
- Novel thermoelectric devices—design, engineering, and integration
- Strategies to enhance thermoelectric efficiency and performance
- Machine learning in thermoelectric materials research
- Machine learning approaches for green energy extraction for sustainable development
- Recent thermoelectric system and applications
- Thermoelectric applications in sustainable energy area
- Concentrated solar thermal thermoelectric design





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Message from the Editor-in-Chief

As the world of science becomes ever more specialized, researchers may lose themselves in the deep forest of the ever increasing number of subfields being created. This open access journal Applied Sciences has been started to link these subfields, so researchers can cut through the forest and see the surrounding, or quite distant fields and subfields to help develop his/her own research even further with the aid of this multi-dimensional network.

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